- Three-State Outputs Interface Directly with System Bus
- 'LS257B and 'LS258B Offer Three Times the Sink-Current Capability of the Original 'LS257 and 'LS258
- Same Pin Assignments as SN54LS157, SN74LS157, SN54S157, SN74S157, and SN54LS158, SN74LS158, SN54S158, SN74S158
- Provides Bus Interface from Multiple Sources in High-Performance Systems

	AVERAGE PROPAGATION	TYPICAL
	DELAY FROM	POWER
	DATA INPUT	DISSIPATIONT
'LS257B	9 ns	55 mW
'LS258B	9 ns	55 mW
'S257	4.8 ns	320 mW
'S258	4 ns	280 mW

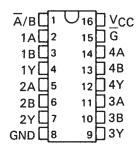
[†]Off state (worst case)

description

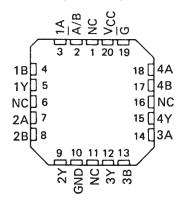
These devices are designed to multiplex signals from four-bit data sources to four-output data lines in busorganized systems. The 3-state outputs will not load the data lines when the output control pin (\overline{G}) is at a high-logic level.

Series 54LS and 54S are characterized for operation over the full military temperature range of -55° C to 125°C; Series 74LS and 74S are characterized for operation from 0°C to 70°C.

SN54LS257B, SN54S257, SN54LS258B, SN54S258 . . . J OR W PACKAGE SN74LS257B, SN74S257, SN74LS258B, SN74S258 . . . D OR N PACKAGE (TOP VIEW)



SN54LS257B, SN54S257, SN54LS258B, SN54S258 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection.

FUNCTION TABLE

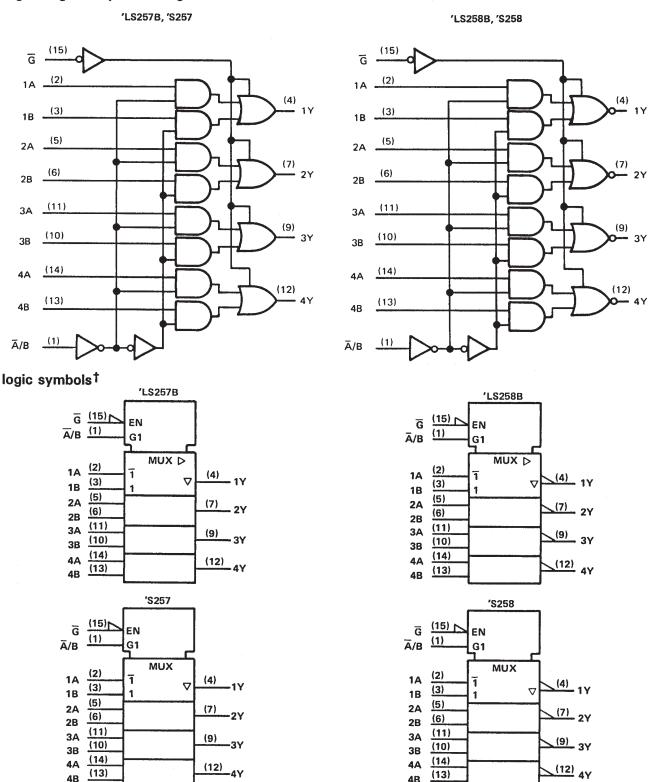
	INPUTS			OUTF	Y TU
OUTPUT CONTROL	SELECT	А	В	'LS257B 'S257	'LS258B 'S258
Н	Х	Х	Х	Z	Z
L	L,	L	Х	L	Н
L.	L	Н	Х	Н	L
L	Н	Х	L.	L	Н
L	Н	Х	Н	Н	L

H = high level, L = low level, X = irrelevant,

Z = high impedance (off)



logic diagrams (positive logic)



[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

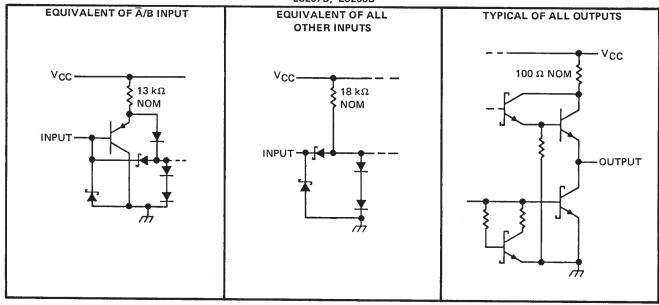


(13)

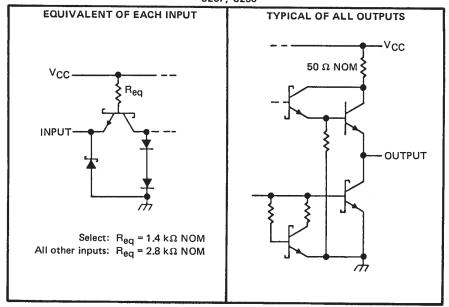
(13)4B

schematics of inputs and outputs

'LS257B, 'LS258B



'S257, 'S258



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: 'LS257B, 'LS258B Circuits	
'S257, 'S258 Circuits	5.5 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54LS', SN54S' Circuits	
	0°C to 70°C
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.



SN54LS257B, SN54LS258B, SN54S257, SN54S258 SN74LS257B, SN74LS258B, SN74S257, SN74S258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SDLS148 - OCTOBER 1976 - REVISED MARCH 1988

recommended operating conditions

			SN54LS'			SN74LS'			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.7			0.8	V	
IOH	High-level output current		· ··	– 1	<u> </u>		- 2.6	mA	
loL	Low-level output current			12			24	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TE	ST CONDITION	ust		SN54LS	3'		SN74LS	3'	
		•	ST CONDITION	40.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK		V _{CC} = MIN,	1 ₁ = 18 mA				- 1.5			- 1.5	V
V _{OH}		V _{CC} = MIN, I _{OH} = MAX	V _{IH} = 2 V,	VIL = MAX,	2.4	3.4		2.4	3.1	, ,	٧
VOL		VCC = MIN,	V _{IH} = 2 V,	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	<u> </u>
-02		VIL = MAX,		I _{OL} = 24 mA		***************************************			0.35	0.5	٧
lozh		V _{CC} = MAX,	V _{IH} = 2 V,	V _O = 2.7 V			20			20	μΑ
lozL		V _{CC} - MAX,	$V_{1H} = 2 V$	V _O = 0.4 V			20			- 20	μΑ
11		V _{CC} = MAX,	V1 = 7 V				0.1			0.1	mA
ΊΗ		V _{CC} = MAX,	V1 = 2.7 V				20			20	μΑ
l _I L_		V _{CC} = MAX,	V _I = 0.4 V				- 0.4			- 0.4	mA
los §		V _{CC} = MAX,			- 30		- 130	- 30		- 130	mA
	All outputs high					8	12		8	12	
	All outputs low			'LS257B		12	18		12	18	1
loo	All outputs off	VMAY	Can Nata O			13	19		13	19	1
lcc	All outputs high	$V_{CC} = MAX$,	See NOTE 2			6	9		6	9	mA
	All outputs low			'LS258B		10	15		10	15	1
	All outputs off					11	16		11	16	1

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}C$.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_{A} = 25^{\circ}\text{C}$. $R_{I} = 667 \Omega$

PARAMETER	FROM	то	TEST CONDITIONS			'LS257	В		'LS258	В				
TATION ETER	(INPUT)	(OUTPUT)	1231 001	MIN	TYP	MAX	MIN	TYP	MAX	UNIT				
^t PLH	Data	Any			8	13		7	12					
^t PHL	Data	Ally	C _L = 45 pF,			10	15		11	17	ns			
^t PLH	Select	Anv		See Note 3		16	21		14	21				
tpHL		Any	Ally	Ally	,,	C[- 45 pr,	See Note S		17	24		19	24	ns
^t PZH	Output	Any			-	15	30		15	30	ns			
^t PZL	Control	City				19	30		20	30				
^t PHZ	Output	Any	C. = 5 nE	Son Note 2		18	30		18	30				
^t PLZ	Control		C _L = 5 pF,	See Note 3		16	25		16	25	ns			

¶tpLH = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

tpzH = output enable time to high level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

tpzL = output enable time to low level

tpHZ = output disable time from high level

tpLZ = output disable time from low level



[§]Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 2: ICC is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

recommended operating conditions

		SN54S'		SN74S'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	CIVIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH			-2			6.5	mA
Low-level output current, IOL			20			20	mA
Operating free-air temperature, TA	55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

							'S257			'S258		UNIT
	PARAME'	TER	TEST	CONDITIONS ¹	ī	MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT
VIH	High-level input	voltage				2			2			V
VIL	Low-level input						., .	0.8			0.8	V
VIK	Input clamp vol		V _{CC} = MIN,	I _I = -18 mA				1.2			-1.2	V
	•		V _{CC} = MIN, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OH} = -1 mA	SN745'	2.7			2.7			v
VOH	OH High-level output voltage		V _{CC} = MIN,	V _{IH} = 2 V,	SN54S'	2.4	3.4		2.4	3.4		,
			$V_{IL} = 0.8 V$,	IOH = MAX	SN74S'	2.4	3.2		2.4	3.2		
VOL	Low-level outpu	ıt voltage	V _{CC} = MIN, V _{IL} = 0.8 V,	V _{1H} = 2 V, I _{OL} = 20 mA				0.5			0.5	٧
lozh	Off-state output	· ·	V _{CC} = MAX, V _O = 2.4 V	V _{IH} = 2 V,				50			50	μА
lozL	Off-state output	· ·	V _{CC} = MAX, V _O = 0.5 V	V _{IH} = 2 V,				-50			-50	μА
l ₁	Input current a	t maximum	V _{CC} = MAX,	V _I = 5.5 V	.,,			1			1	mA
	High-level	Sinput		07.1				100			100	μΑ
۱нн	input current	Any other	V _{CC} = MAX,	, V ₁ = 2.7 V				50			50] "
	Low-level	S input		0.5.1/				4			-4	mA
11L	input current	Any other	V _{CC} = MAX	V I = 0.5 V				-2			-2	
los	Short-circuit ou	itput current§	V _{CC} = MAX			-40		-100	-40		-100	mA
		All outputs high					44	68		36	56	1
ICC	Supply current	All outputs low	VCC = MAX	, See Note 2			60	93		52	81	mA
		All outputs off]				64	99		56	87	

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, $TA = 25^{\circ}\text{C}$, $RL = 280 \Omega$

	FROM	то	TEST		'S257			'S258		UNIT
PARAMETER¶	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
tPLH	5-1-	A ===			5	7.5		4	6	ns
tPHL tPHL	Data	Any			4.5	6.5		4	6] '''
tPLH	0.1	A	$C_L = 15 pF$,		8.5	15		8	12	ns
tPHL	Select	Any	See Note 3		8.5	15		7.5	12	113
tPZH	Output				13	19.5		13	19.5	ns
tPZL	Control	Any			14	21		14	21	1 "
tPHZ	Output	_	$C_L = 5 pF$,		5.5	8.5		5.5	8.5	200
t _{PLZ}	Control	Any	See Note 3		9	14		9	14	ns

[¶]f_{max} = Maximum clock frequency

 $t_{PZL} \equiv$ output enable time to low level $t_{PHZ} \equiv$ output disable time from high level





[‡]All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 2: ICC is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

tpLH = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

tpZH = output enable time to high level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
7603701EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603701EA SNJ54LS257BJ	Sample
7603701FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603701FA SNJ54LS257BW	Sample
7603701FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603701FA SNJ54LS257BW	Sample
7603801EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603801EA SNJ54LS258BJ	Sample
7603801EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603801EA SNJ54LS258BJ	Sample
8002301EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301EA SNJ54S258J	Sample
8002301EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301EA SNJ54S258J	Sample
8002301FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301FA SNJ54S258W	Sample
8002301FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301FA SNJ54S258W	Sample
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BEA	Sample
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BEA	Sample
JM38510/07906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BFA	Sample
JM38510/07906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BFA	Sampl
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906B2A	Sampl
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906B2A	Sample
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BEA	Sample





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BEA	Samples
JM38510/30906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BFA	Samples
JM38510/30906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BFA	Samples
M38510/07906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BEA	Samples
M38510/07906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BEA	Samples
M38510/07906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BFA	Samples
M38510/07906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BFA	Samples
M38510/30906B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906B2A	Samples
M38510/30906B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906B2A	Samples
M38510/30906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BEA	Samples
M38510/30906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BEA	Samples
M38510/30906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BFA	Samples
M38510/30906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BFA	Samples
SN54LS257BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS257BJ	Samples
SN54LS257BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS257BJ	Samples
SN54LS258BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS258BJ	Samples
SN54LS258BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS258BJ	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN54S257J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S257J	Samples
SN54S257J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S257J	Samples
SN74LS257BD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS257B	Samples
SN74LS257BD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS257B	Samples
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS257B	Samples
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS257B	Samples
SN74LS257BN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS257BN	Samples
SN74LS257BN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS257BN	Samples
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS257B	Samples
SN74LS257BNSR	ACTIVE	so	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS257B	Samples
SN74LS258BD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS258B	Samples
SN74LS258BD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS258B	Samples
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS258B	Samples
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS258B	Samples
SN74LS258BN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS258BN	Samples
SN74LS258BN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS258BN	Samples
SN74S257N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S257N	Samples
SN74S257N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S257N	Samples
SNJ54LS257BFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 257BFK	Samples
SNJ54LS257BFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 257BFK	Samples



SNJ54S258J

8002301EA

SNJ54S258J

8002301FA

8002301FA

SNJ54S258W

SNJ54S258W

Samples

Samples

Samples

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Orderable Device Package Type Package Pins Package **Eco Plan** Lead finish/ MSL Peak Temp Op Temp (°C) **Device Marking** Samples Status Drawing Qty **Ball material** (1) (2) (3) (4/5)(6) SNJ54LS257BJ **ACTIVE** CDIP J 16 1 Non-RoHS SNPB N / A for Pkg Type -55 to 125 7603701EA Samples & Green SNJ54LS257BJ SNJ54LS257BJ **ACTIVE** CDIP J 16 1 Non-RoHS **SNPB** N / A for Pkg Type -55 to 125 7603701FA Samples & Green SNJ54LS257BJ SNJ54LS257BW **ACTIVE** CFP W 16 1 Non-RoHS **SNPB** N / A for Pkg Type -55 to 125 7603701FA Samples & Green SNJ54LS257BW SNJ54LS257BW **ACTIVE CFP** W 16 1 Non-RoHS **SNPB** N / A for Pkg Type -55 to 125 7603701FA Samples & Green SNJ54LS257BW SNJ54LS258BJ **ACTIVE** CDIP J 16 1 Non-RoHS SNPB N / A for Pkg Type -55 to 125 7603801EA Samples & Green SNJ54LS258BJ SNJ54LS258BJ **ACTIVE** CDIP J 16 1 Non-RoHS **SNPB** N / A for Pkg Type -55 to 125 7603801EA Samples & Green SNJ54LS258BJ SNJ54S257J **ACTIVE CDIP** J 16 1 Non-RoHS **SNPB** N / A for Pkg Type -55 to 125 SNJ54S257J Samples & Green SNJ54S257J ACTIVE CDIP J 16 Non-RoHS **SNPB** N / A for Pkg Type SNJ54S257J 1 -55 to 125 Samples & Green SNJ54S257W ACTIVE **CFP** W 16 1 Non-RoHS **SNPB** N / A for Pkg Type -55 to 125 SNJ54S257W Samples & Green SNJ54S257W ACTIVE **CFP** W 16 1 Non-RoHS SNPB N / A for Pkg Type -55 to 125 SNJ54S257W Samples & Green 16 1 Non-RoHS **SNPB** 8002301EA SNJ54S258J ACTIVE CDIP J N / A for Pkg Type -55 to 125 Samples

SNPB

SNPB

SNPB

N / A for Pkg Type

N / A for Pkg Type

N / A for Pkg Type

-55 to 125

-55 to 125

-55 to 125

SNJ54S258J

SNJ54S258W

SNJ54S258W

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

CDIP

CFP

CFP

J

W

W

ACTIVE

ACTIVE

ACTIVE

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

16

16

16

1

1

1

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

& Green

Non-RoHS

& Green

Non-RoHS

& Green

Non-RoHS

& Green

⁽¹⁾ The marketing status values are defined as follows:

PACKAGE OPTION ADDENDUM

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(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS257B, SN54LS258B, SN54S257, SN74LS257B, SN74LS258B, SN74S257:

Catalog: SN74LS257B, SN74LS258B, SN74S257

Military: SN54LS257B, SN54LS258B, SN54S257

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS257BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS257BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS258BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS257BDR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LS257BNSR	SO	NS	16	2000	853.0	449.0	35.0
SN74LS258BDR	SOIC	D	16	2500	340.5	336.1	32.0



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/07906BFA	W	CFP	16	1	506.98	26.16	6220	NA
JM38510/30906B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/07906BFA	W	CFP	16	1	506.98	26.16	6220	NA
M38510/30906B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74LS257BD	D	SOIC	16	40	507	8	3940	4.32
SN74LS257BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS257BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS258BD	D	SOIC	16	40	507	8	3940	4.32
SN74LS258BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS258BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74S257N	N	PDIP	16	25	506	13.97	11230	4.32
SN74S257N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS257BFK	FK	LCCC	20	1	506.98	12.06	2030	NA

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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